

REMARKS

Claims 2, 4, 11-12, and 16 are pending in the application. Claims 1, 3, 5-10, 13-15, and 17-20 have been cancelled.

The Examiner's remarks in the Office Action dated May 17, 2007 and the Advisory Action dated October 3, 2007 have been carefully considered. The Examiner's reconsideration is respectfully requested in light of the following remarks and amendments to the claims.

Amendments to the Claims

Claims 2 and 11 have each been amended to recite, *inter alia*, "whereby said circular laminated protective sheet prevents vibration and damage to the wafer during backgrinding and transportation." Basis for this Amendment can be found, for example, in the specification on page 2, lines 9-10; page 4, lines 7-10; page 7, lines 7-9; page 29, lines 5-8; and in the Abstract, lines 8-11. Claims 2 and 11 have each also been amended to recite, *inter alia*, "and the first circular protective layer includes a film having a stress relaxation rate of at least 40% after 1 minute of 10% elongation, and the second circular protective layer includes a film having a value of Young's modulus x thickness of at least 5.0×10^4 N/m." Basis for this Amendment can be found, for example, in the specification, on page 5, lines 19-22. Accordingly, no new matter has been added.

Rejections Under 35 U.S.C. §102(a) and 35 U.S.C. §103(a)

Claims 1 and 11 presently stand rejected under 35 U.S.C. §102(a) as being anticipated by United States Patent Publication No. 2003/0003688 to Tandy et al. (hereinafter "Tandy"). Claim 1 has been canceled. Claims 2-5, 12-13, 16-17 and 20 presently stand rejected under 35 U.S.C. §103(a) as being unpatentable over Tandy. Claims 3, 5, 13, and 17-20 have been canceled.

Applicants submit that Tandy does not disclose or suggest the invention recited in amended independent claims 2 and 11. Specifically, amended claims 2 and 11 presently recite, in relevant part, "whereby said circular laminated protective sheet prevents vibration and damage to the wafer during backgrinding and transportation." In contrast, as recited on page 4, paragraph [0034], of Tandy:

laser markable tape 1, also referred to as "marking tape 1," is applied to a backside surface 12 of semiconductor wafer 10 after it

has been thinned through a backgrinding process (emphasis added).

Tandy also recites on page 4, paragraph [0036], that:

Use of the terms "laser markable tape" and "marking tape" are intended to refer to any tape configured such that, upon impact or heating by a laser, component or inherent characteristics of the tape allow for the formation or transfer of a distinct and permanent or semi-permanent mark onto a surface of a semiconductor die.

Accordingly, the "laser markable tape 1" or "marking tape 1" of Tandy is applied to the semiconductor after grinding and is structured to impart a feature onto the semiconductor surface.

In contrast, as recited on page 2, lines 9-10 of Applicants' disclosure, Applicants' protective surface is intended to "prevent vibration of the protective sheet during the backgrinding" (emphasis added). Applicants' protective sheet is intended to prevent alteration of the semiconductor wafer. Tandy's marking tape 1 is intended to allow for formation or transfer of a distinct and permanent or semi-permanent mark onto the semiconductor surface. Accordingly, the purpose of the marking tape 1 of Tandy is entirely distinct from the purpose of the presently claimed protective layer.

In addition, claims 2 and 11 have been amended to recite, in relevant part, "the first circular protective layer includes a film having a stress relaxation rate of at least 40% after 1 minute of 10% elongation, and the second circular protective layer includes a film having a value of Young's modulus x thickness of at least 5.0×10^4 N/m." Applicants submit that Tandy fails to disclose or suggest a first circular protective layer having a stress relaxation rate of at least 40% after 1 minute of 10% elongation. Applicants further submit that Tandy fails to disclose or suggest a second circular protective layer includes a film having a value of Young's modulus x thickness of at least 5.0×10^4 N/m. As described in Applicant's specification on page 20, lines 6-13, when the laminated sheet of Applicants' invention is ground to an ultra-thin thickness, the sheet can be supported without curvature because of very small residual stresses in the laminated sheet as a whole. In contrast, the marking tape of Tandy is not a tape for preventing vibration and damage to the wafer during backgrinding and transportation. Tandy does not disclose or suggest a protective layer which "prevents vibration and damage to the wafer during backgrinding and transportation" as recited by amended claims 2 and 11. Accordingly, Applicants request reconsideration and withdrawal of the rejection of claims 2 and 11.

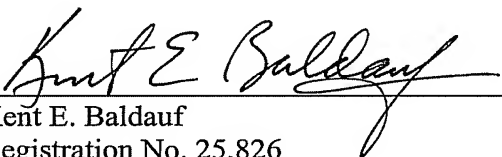
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Dependent claims 4 and 16 depend directly from independent claim 2 and are believed patentable for the reasons stated herein. Dependent claim 12 depends directly from independent claim 11 and is believed patentable for the reasons stated herein. Reconsideration and withdrawal of the rejection of claims 4, 12 and 16 is requested.

SUMMARY

Applicants respectfully submit that the presently claimed invention is patentably distinct over the above-identified prior art of record and that claims 2, 4, 11-12, and 16 are in condition for allowance. The Examiner's reconsideration and favorable action with respect to claims 2, 4, 11-12, and 16 is respectfully requested.

Respectfully submitted,
THE WEBB LAW FIRM

By 
Kent E. Baldauf
Registration No. 25,826
Attorney for Applicants
700 Koppers Building
436 Seventh Avenue
Pittsburgh, Pennsylvania 15219
Telephone: 412-471-8815
Facsimile: 412-471-4094
E-Mail: webblaw@webblaw.com